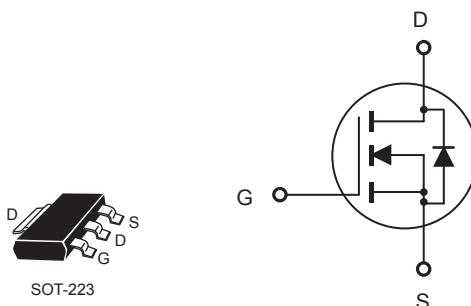


## N-Channel Enhancement Mode Field Effect Transistor

PRELIMINARY

## FEATURES

- 650V, 0.3A,  $R_{DS(ON)} = 15\Omega$  @ $V_{GS} = 10V$ .
- High dense cell design for extremely low  $R_{DS(ON)}$ .
- Rugged and reliable.
- Lead-free plating ; RoHS compliant.
- SOT-223 package.

ABSOLUTE MAXIMUM RATINGS  $T_A = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	0.3	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	1.2	A
Maximum Power Dissipation	$P_D$	3	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	42	$^\circ C/W$



# CET01N65A

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 0.2\text{A}$		12	15	$\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		170		pF
Output Capacitance	$C_{\text{oss}}$			60		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			30		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_{\text{D}} = 0.3\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 4.7\Omega$		10	20	ns
Turn-On Rise Time	$t_r$			11	22	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			24	48	ns
Turn-Off Fall Time	$t_f$			62	124	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 480\text{V}, I_{\text{D}} = 0.3\text{A}, V_{\text{GS}} = 10\text{V}$		10	12.8	nC
Gate-Source Charge	$Q_{\text{gs}}$			0.6		nC
Gate-Drain Charge	$Q_{\text{gd}}$			7.5		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				0.3	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 0.2\text{A}$			1.5	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board,  $t \leq 10 \text{ sec.}$
- c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- d.Guaranteed by design, not subject to production testing.

**CET**

# CET01N65A

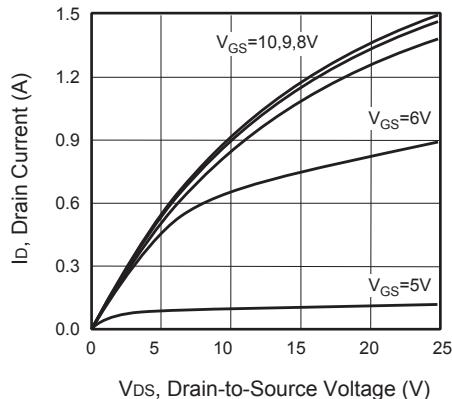


Figure 1. Output Characteristics

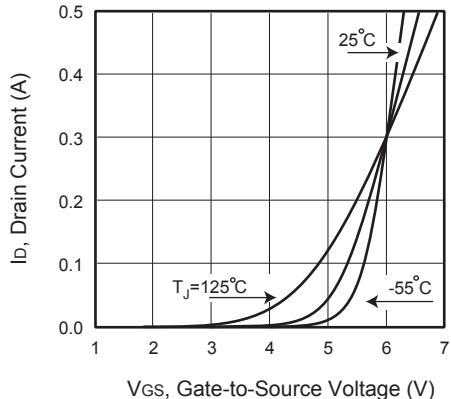


Figure 2. Transfer Characteristics

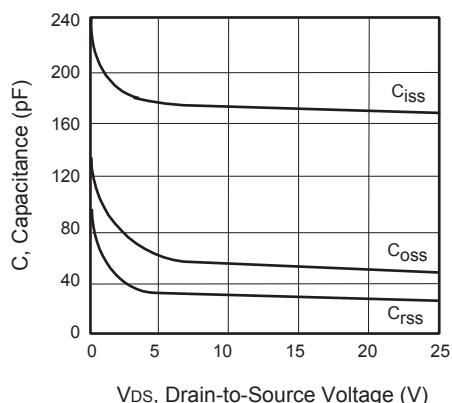


Figure 3. Capacitance

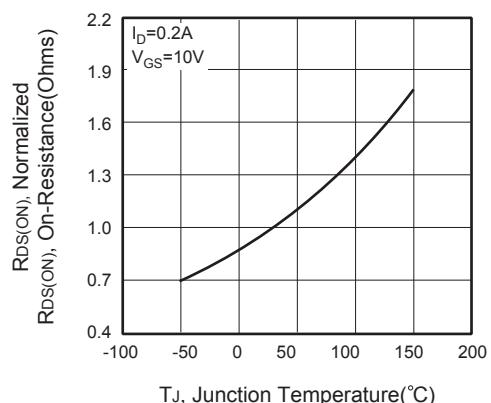


Figure 4. On-Resistance Variation with Temperature

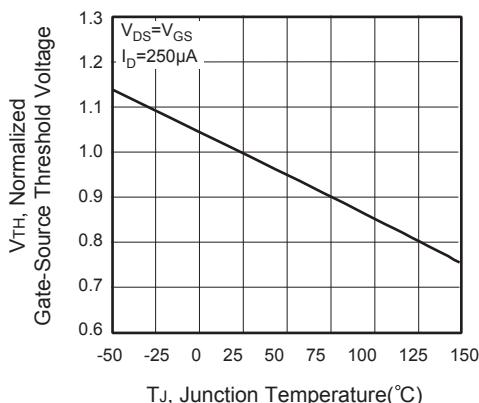


Figure 5. Gate Threshold Variation with Temperature

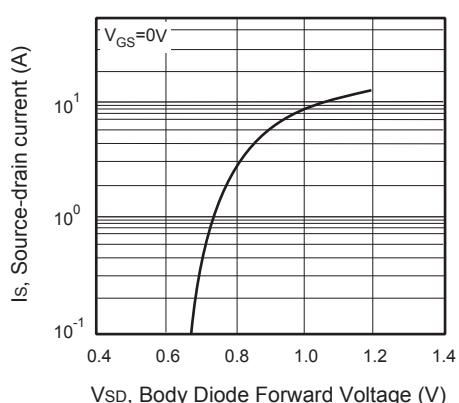
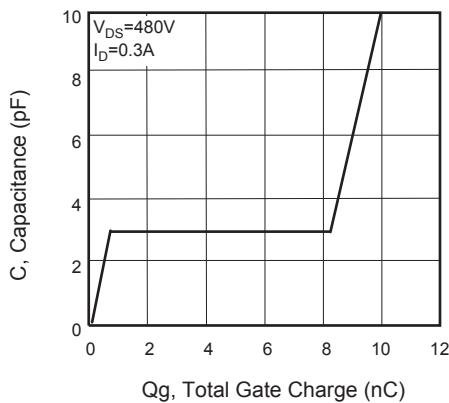
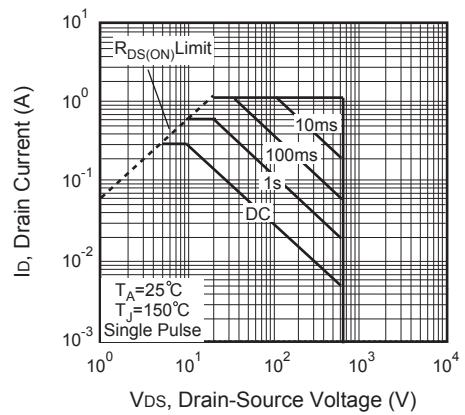


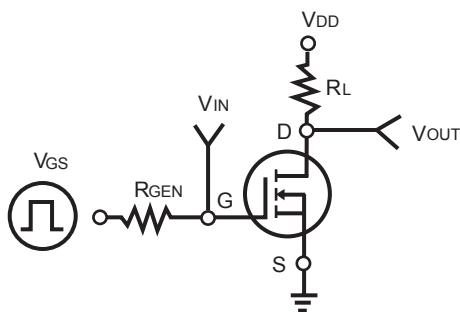
Figure 6. Body Diode Forward Voltage Variation with Source Current



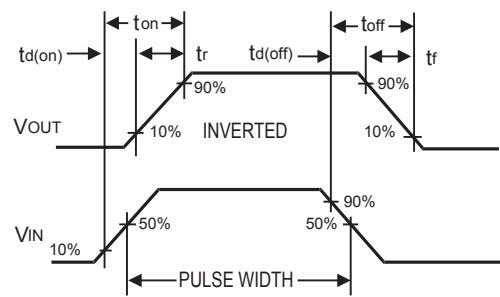
**Figure 7. Gate Charge**



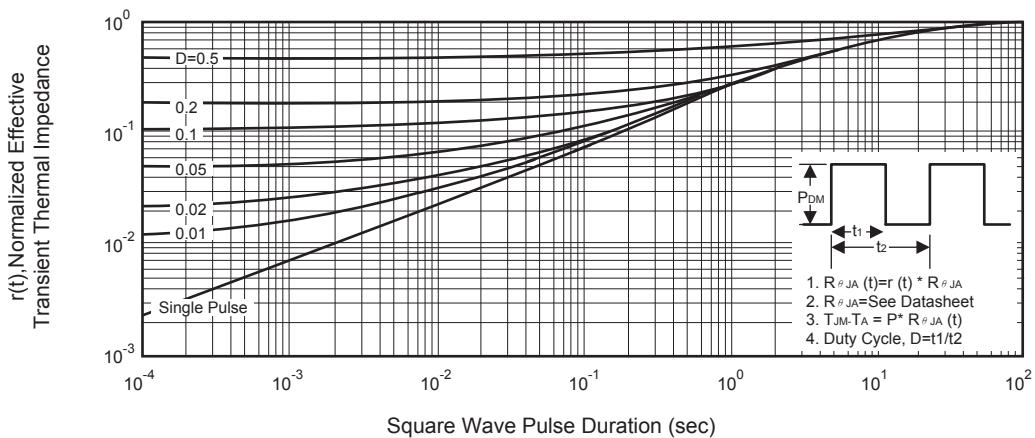
**Figure 8. Maximum Safe Operating Area**



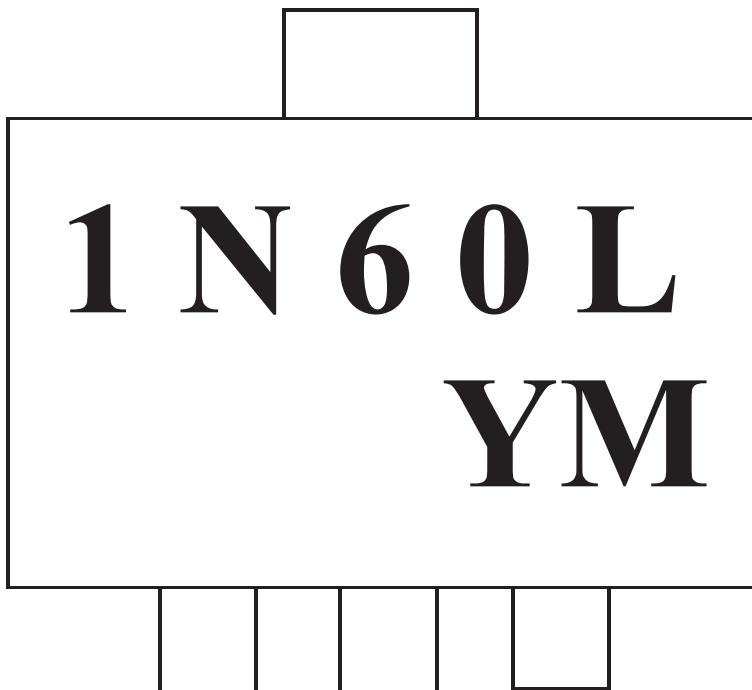
**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**

**Marking Rule**

**Y→year**

0	1	2	3	4	5	6	7	8	9
N	O	P	Q	R	S	T	U	V	W

**M→month**

1	2	3	4	5	6	7	8	9	10	11	12
A	B	C	D	E	F	G	H	J	K	L	M